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## TR-42: Engineering Committee on Premises Telecommunications Cabling

**Date:** June 12, 2007

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**From:** Herb Congdon, Chair, TR-42 ([hvcongdon@tycoelectronics.com](mailto:hvcongdon@tycoelectronics.com))

**Subject:** Unmating connectors under electrical load

Thank you for your liaison dated November 16th, 2006. It is our understanding that the life expectancy of connecting hardware when unmated under load is under discussion in IEC SC48B, the subcommittee responsible for the IEC 60603-7 series of modular connectors. Since TIA references IEC 60603-7 for connecting hardware reliability performance, we intend to defer to their final recommendations.

Best regards,

Herb Congdon